

To. :

DATE : 20 . . .

RoHS 1,2 and 3	Halogen Free
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SPECIFICATION

PRODUCT : Chipcell Carbon

MODEL : DMS3R3224RF

WRITTEN	CHECKED	APPROVED

KORCHIP CORP.

KORCHIP B/D, 359, Manan-ro, Manan-gu, Anyang-si, Gyeonggi-do, KOREA

TEL : 82 - 31 - 361 - 8000

FAX : 82 - 31 - 361 - 8080

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Revision History

No.	Documentation	Check	Description of Revision	Approval	Date
1	S.H. Jeon (R&D)	K.B. Chung (Q.A.)	Initial Release	B.I. Lim (R&D)	Mar. 23, 2023

Manufacturer Information

Manufacturer : Korchip Corporation

Location : KORCHIP B/D, 359, Manan-ro, Manan-gu, Anyang-si, Gyeonggi-do,
KOREA

Tel. : +82-31-361-8000

Fax. : +82-31-361-8080

1. Scope

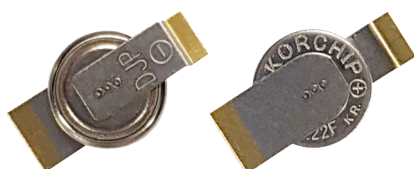
This specification applies to Chipcell Carbon 2nd. battery, submitted to specified customer in cover page.

2. Part Number System

<u>DMS</u>	<u>3R3</u>	<u>224</u>	<u>RF</u>
①	②	③	④

- ① Series Name : DMS
- ② Rated Voltage : 3.3VDC
- ③ Capacitance : 0.22 F (224 = $22 \times 10^{+4}$ uF)
- ④ Special Code

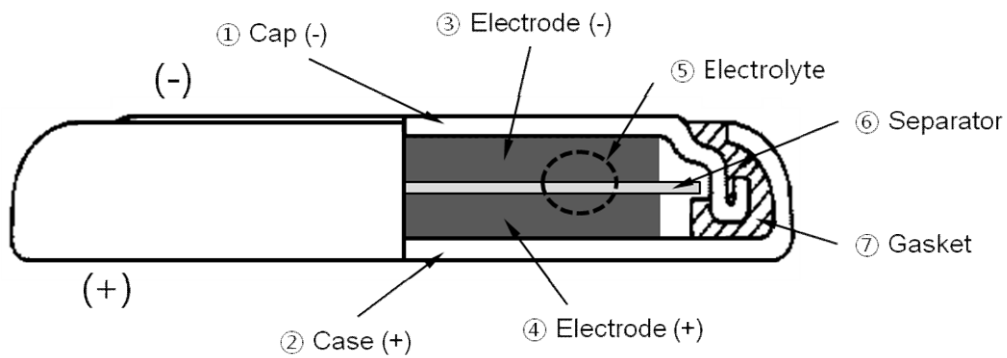
3. Photo



4. General Specifications

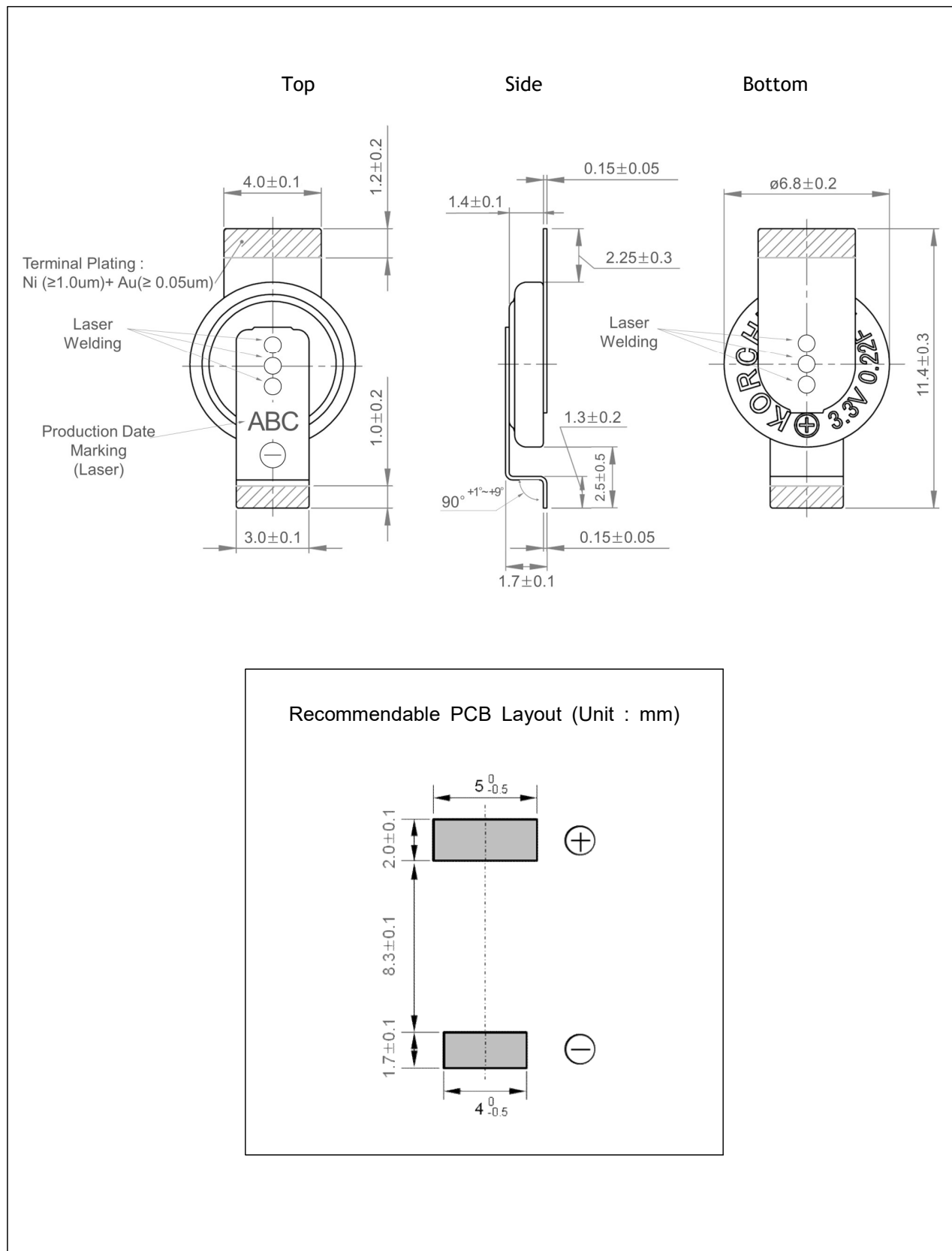
ITEMS	VALUE
Rated Voltage	3.3 VDC
Operating Temp.	-10 ~ +60 ℃
Capacitance (F)	0.22 F
Capacitance Tolerance	-20 ~ 80 %
Equivalent Series Resistance (ESR)	Less than 200Ω

5. Cell Structure



Part Name	Material
① Cap (-)	Stainless Steel
② Case (+)	Stainless Steel
③ Electrode (-)	Activated Carbon
④ Electrode (+)	Activated Carbon
⑤ Electrolyte	Organic Electrolyte
⑥ Separator	Polypropylene
⑦ Gasket	Engineering Plastic

6. Appearance and Dimensions



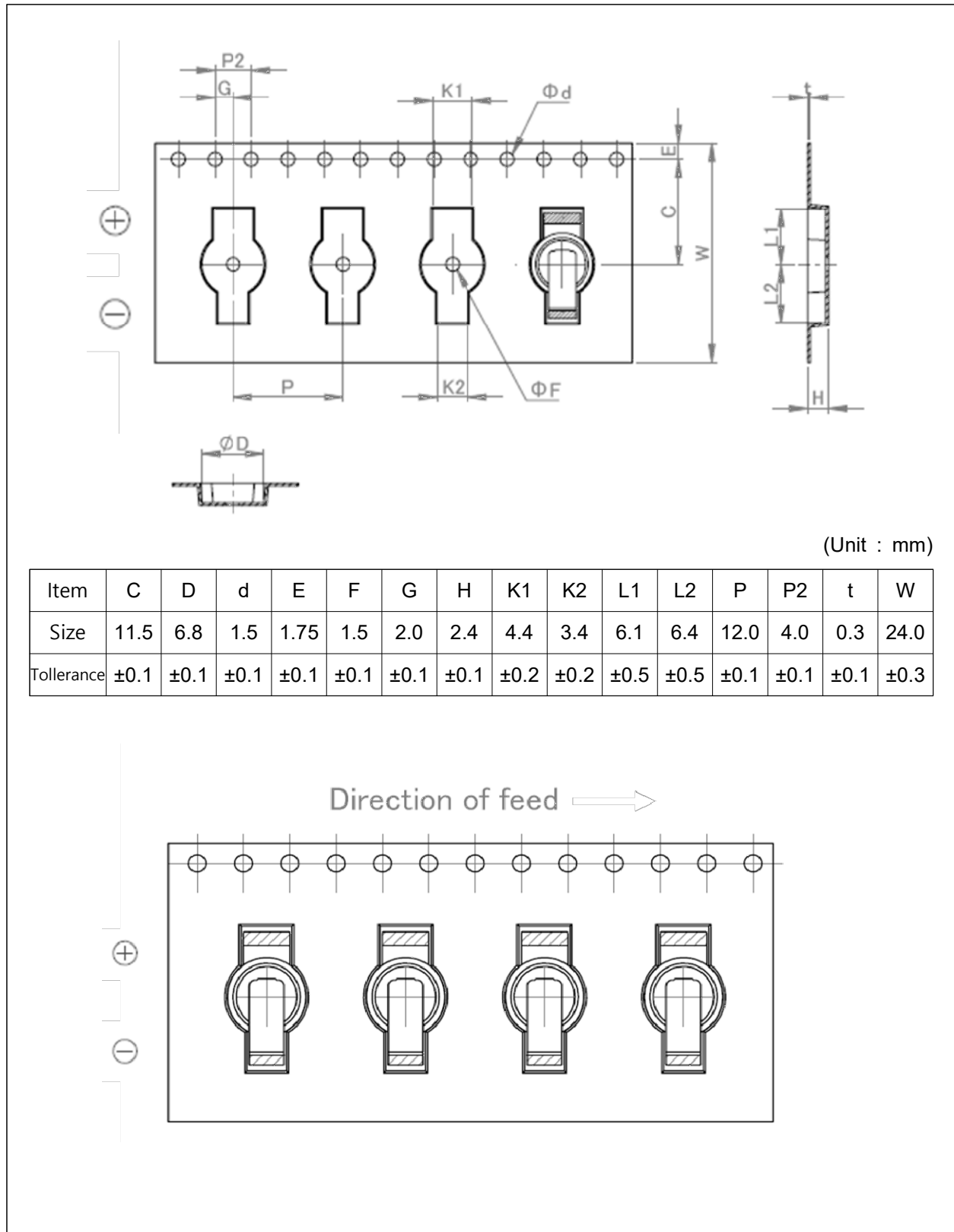
7. Reliability Specifications

Item		Specification		Test Condition													
Temperature Characteristics	Capacitance Change	Step 2	Within ± 30% of Initial Value	Measure electrical characteristics after exposing Chipcell Carbon to each temperature atmosphere for one(1) hour <table><tr><td>Step</td><td>Temperature</td></tr><tr><td>1</td><td>20±2℃</td></tr><tr><td>2</td><td>-10±2℃</td></tr><tr><td>3</td><td>20±2℃</td></tr><tr><td>4</td><td>60±2℃</td></tr><tr><td>5</td><td>20±2℃</td></tr></table>		Step	Temperature	1	20±2℃	2	-10±2℃	3	20±2℃	4	60±2℃	5	20±2℃
	Step		Temperature														
	1	20±2℃															
	2	-10±2℃															
	3	20±2℃															
	4	60±2℃															
5	20±2℃																
ESR	5Times or less than Initial Value																
Capacitance Change	Step 4	Within ± 30% of Initial Value															
ESR		200Ω or less															
Capacitance Change	Step 5	Within ± 10% of Initial Value															
ESR Change		200Ω or less															
Reflow Soldering Effect	Capacitance	Spec. Value		Pb-Free Reflow Solder Peak Temp. : 260± 5℃ Duration at Peak Temp. : 5±0.5℃													
	Appearance	No Marked Defect (Level 2* or less)															
Humidity Resistance	Capacitance Change	± 30% of Initial Value		Temp. : 40±2℃ Humidity : 90 ~ 95%RH Time : 500±8 Hours No Voltage Applied													
	ESR	2KΩ or less															
	Appearance	No Marked Defect (Level 2* or less)															
Self Discharge Characteristics	Voltage	More than 1.8Vdc	Charging Condition	Voltage : 3.3Vdc Current : 20mA Charge Time : 24 Hours													
			Self Discharge Condition	Duration : 24 Hours Temp. : Less than 25℃ Humidity : Less than 70%RH													
Vibration Resistance	Capacitance	Spec. Value		Amplitude : 1.5mm Frequency : 10 ~ 55Hz Direction : X, Y, Z 3 Directions Test Time : 6 Hours													
	ESR	Spec. Value															
	Appearance	No Marked Defect (Level 2* or less)															
Terminal Strength	Appearance	Terminals shall not be separated	Load 10N , 10±1 Sec.														
Terminal Bend Strength			Load 5N , Angle 90° , 1Cycle														
Endurance	Capacitance Change	Within ± 30% of Initial Value		Temp. : 60±2℃ Test Time : 1,000(+24,-0) Hours Applied Voltage : 3.3Vdc													
	ESR	2KΩ or less															
	Appearance	No Marked Defect (Level 2* or less)															
Shelf Life	Capacitance Change	Within ± 30% of Initial Value		Temp. : 60±2℃ Test Time : 1,000(+24,-0) Hours No Voltage Applied													
	ESR	2KΩ or less															
	Appearance	No Marked Defect (Level 2* or less)															

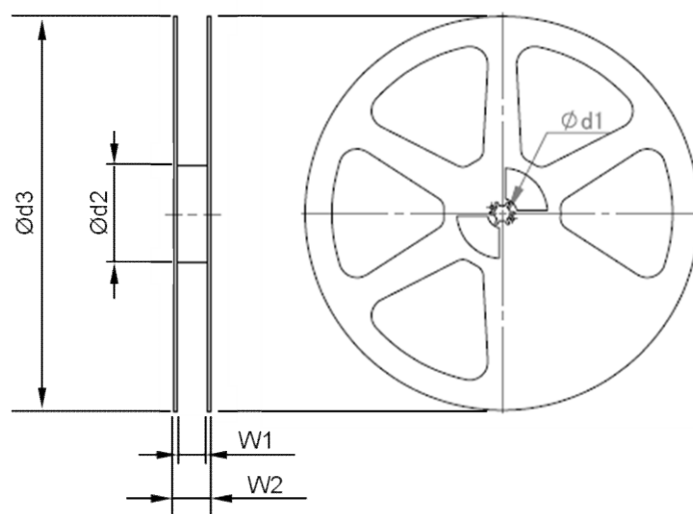
* Refer to "13. Leakage Level Criteria" on page 16

8. Packing Specifications

1) Carrier Tape

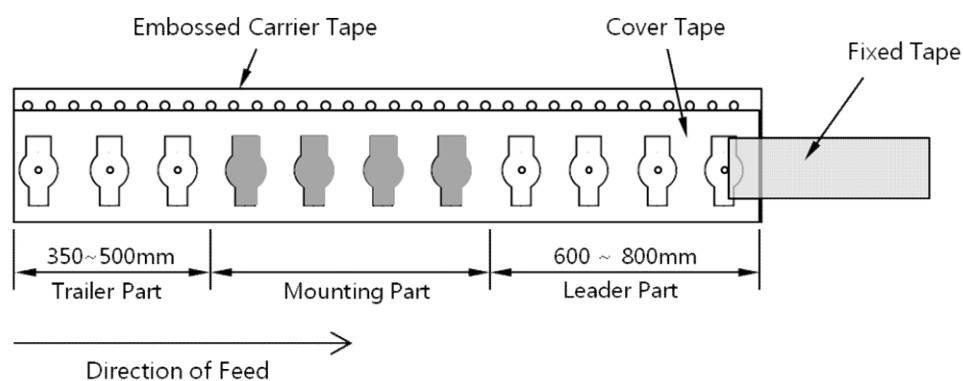
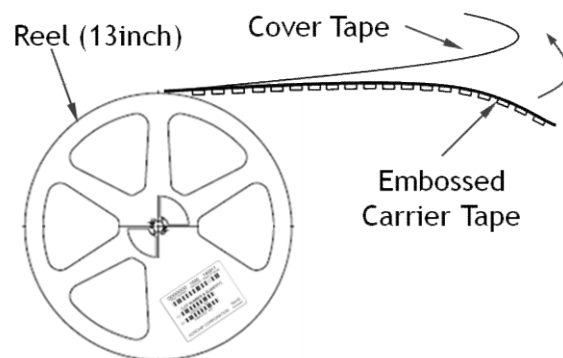


2) Reel

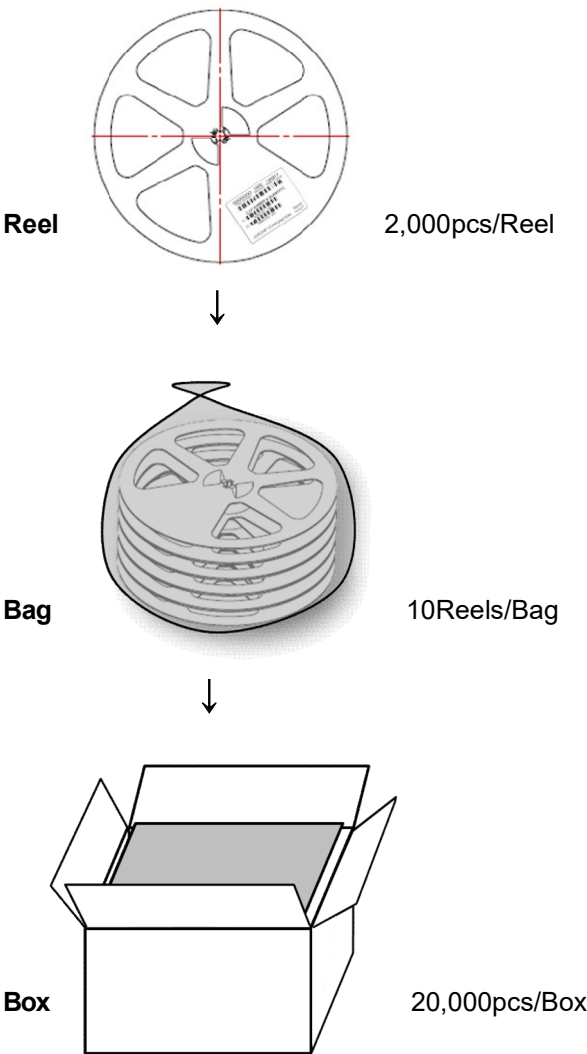


(Unit : mm)

W1	W2	Ød1	Ød2	Ød3
25±0.5	(29.5±1)	13±0.5	80±1	330±1 (13inch)

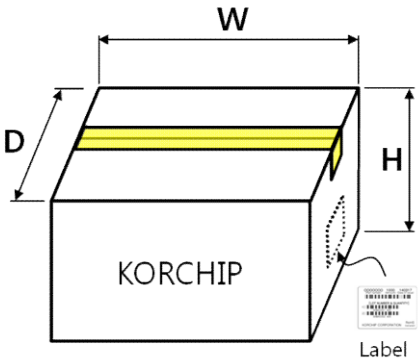


3) Box



	Unit	Reel	Bag	Box
Weight	0.22g	0.90kg	9.0kg	10kg
Qty. (pcs)	1	2,000	20,000	20,000

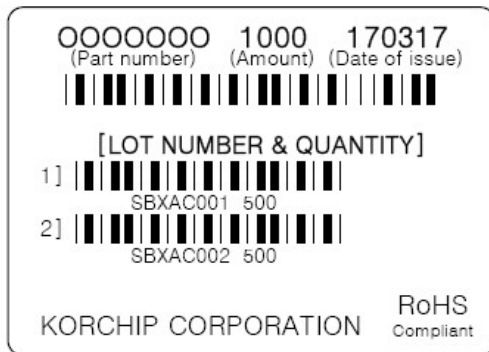
<Weight Information>



W	D	H
350mm	350mm	370mm

<Box Dimension>

9. Labeling Standards



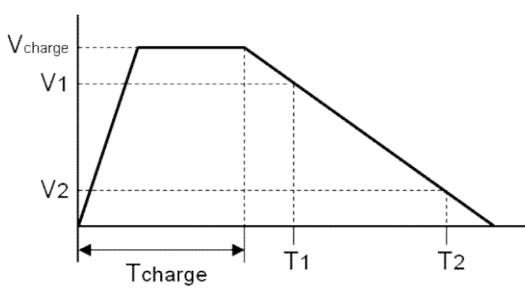
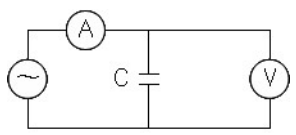
← (Example)

Lot No. System

Ex.) S H X A C 002
 ① ② ③ ④ ⑤ ⑥

- ① Product Code : S (Chipcell Carbon)
- ② Production Year Code : A (2016), B (2017), ... , F (2021), G (2022), H (2023)...
- ③ Factory Identification Code : X (Factory X)
- ④ Production Month Code : A (Jan.), B (Feb.), ... , J (Oct.), K (Nov.), L (Dec.)
- ⑤ Production Date Code : 1 (1st), 2 (2nd), ... , 9 (9th), A (10th), B (11th), C (12th) ...
 Q (26th), R (27th), S (28th), ... , V (31th)
- ⑥ Lot Issuing Serial Code : 001 (First lot of a specific day), 002 (Second lot of a specific day), 003 (Third lot of a specific day)...

10. Measuring Method of Characteristics

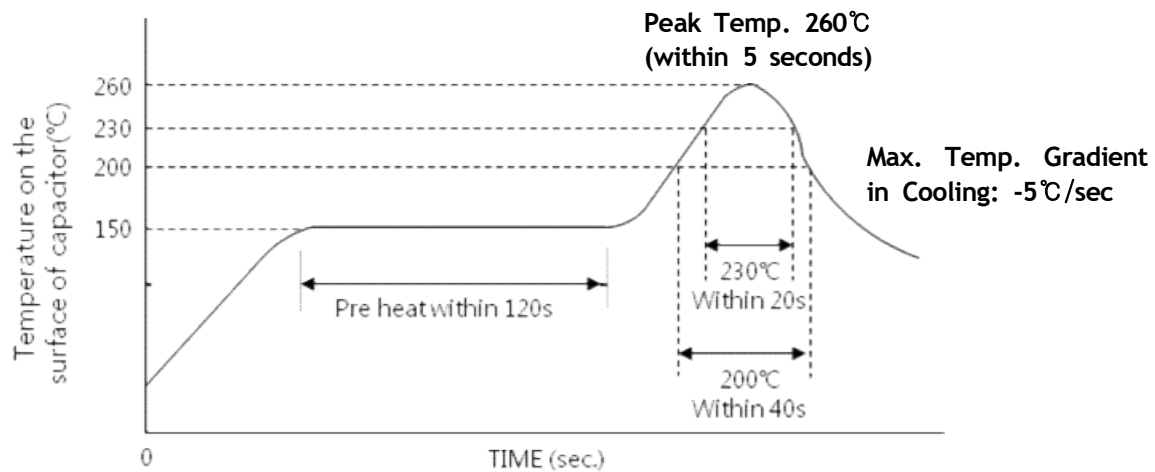
Capacitance	1) Charge the Chipcell Carbon with constant current $I_{\text{charge}} (=1 \pm 0.1 \text{ mA})$ to $V_{\text{charge}} (=3.3 \text{ V})$ then keep charging for $T_{\text{charge}} (=3000 \text{ sec.})$ 2) Discharge the Chipcell Carbon with constant current $I_{\text{disch}} (=0.5 \text{ mA})$ while measure the discharge time T_1, T_2 between $V_1 (=2.64 \text{ V})$ and $V_2 (=1.32 \text{ V})$. 3) Calculate capacitance using the following formula.  $C = \frac{I_{\text{disch}} \times (T_1 - T_2)}{V_1 - V_2}$
Equivalent Series Resistance (ESR @1kHz)	- Measure ESR by the LCR meter. (Frequency:1kHz, Bias Voltage : $0^{+0.05} \text{ V}$) or - Calculate ESR using the following formula.  $\text{ESR} [\Omega] = V / i$ $R [\Omega] = V [\text{V}] / I [\text{A}] \quad * i [\text{mA}] = I [\text{A}] \times 10^{-3}$ R : Internal resistance(ESR) [Ω] V : Measured voltage between terminals [V] i : Current 1mA(A.C.)
☞ The Chipcell Carbon should be shorted before each measurement as follows ; Capacitance : 60 min. , ESR : 15 min. , LC : 15 min.	

11. Mounting

1) Reflow Soldering

Excessive heat stress may result in the deterioration of the electrical characteristics of the capacitor and electrolyte leakage due to the rise in internal pressure.

Use the general reference chart then set soldering temperature and time.



The time of repeated reflow soldering must be two times or less.

Do not use reflow soldering when the cell voltage is above 0.3V.

2) Manual Soldering

For use of a soldering iron, it should not touch the cell body.

Temperature of the soldering iron should be less than 360°C.

Soldering time for terminals should be less than 3(-0/+1) seconds.

12. Cautions for Use

Please be careful for following points when you use Korchip's Chipcell Carbon.

1) Do not apply more than rated voltage.

If you apply more than rated voltage, electrolyte in Chipcell Carbon will be decomposed and its ESR increase. At the worst, it may be broken.

2) Do not use Chipcell Carbon for ripple absorption.

3) Polarity

Please mount it in accordance with its polarity.

4) Operating environment and lifetime

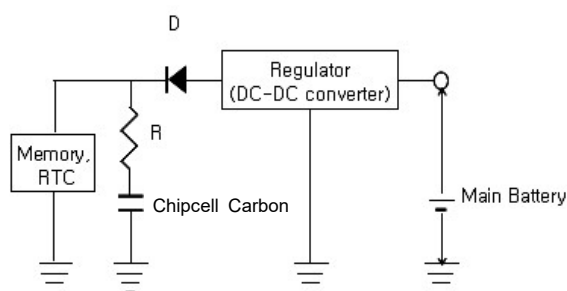
Chipcell Carbon shows faster deterioration in high temperature operation. The lifetime of Chipcell Carbon follows the general lifetime acceleration rule of double or half per every 10°C of ambient temperature decrease or increase respectively. A large temperature difference in one day or humid operating environment results in dew condensation on the surface of Chipcell Carbon and it may cause fast deterioration or electrolyte leakage of Chipcell Carbon.

If the Chipcell Carbon is used in an electronic or electrical device over a long period of time especially in high temperature or high humidity environment, please check it periodically and replace it when necessary.

5) Cleaning

Some detergent or high temperature drying causes deterioration of Chipcell Carbon. If you wash Chipcell Carbon products, Consult us.

6) Following figure shows the general back-up circuit.



D : Diode to prevent the reverse current
R : Resistor to control the charging current

7) Short-circuit

DO NOT short-circuit between terminals of Chipcell Carbon products without resistor.

8) Storage

In long term storage, please store Chipcell Carbon products in following condition;

- ① TEMP. : 15 ~ 35 °C
- ② HUMIDITY : Less than 60%RH
- ③ Non-dust, non-acidic and/or non-alkaline atmosphere
- ④ Avoid direct sun light, strong magnetic field

Storage period limit is one(1) year when an Chipcell Carbon is stored in the above condition. Storage in improper condition may cause some damage to the Chipcell Carbon. If the storage period exceed one(1) year in the customer's warehouse, please contact the manufacturer.

9) Do not disassemble the Chipcell Carbon. It contains electrolyte.

10) Series connection of Chipcell Carbon products

Over-rated voltage may be applied to a single Chipcell Carbon in series connection due to the deviation of capacitance and ESR of each Chipcell Carbon . Please inform us if you are using Chipcell Carbon products in series connection and please design so as not to apply over-rated voltage to each Chipcell Carbon, and use Chipcell Carbons from a same lot.

11) The tips or edges of an Chipcell Carbon terminals are very sharp. Please handle with care.

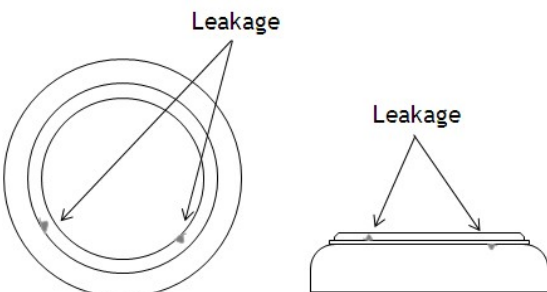
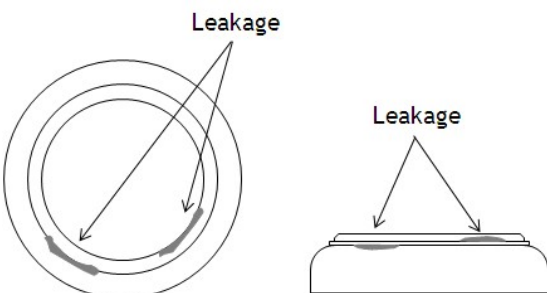
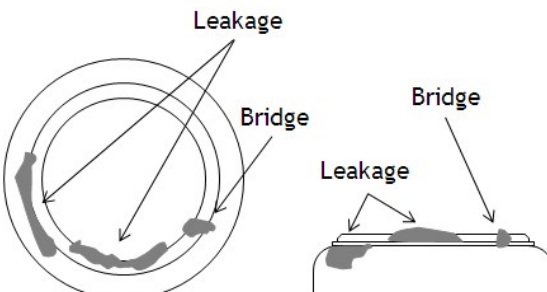
12) Industrial Application

Some industrial applications require a very high level of reliability to its parts including Chipcell Carbon. Therefore if the Chipcell Carbon is to be used in an industrial application such as factory machinery, heavy electricity, etc. periodic inspection of Chipcell Carbon is necessary. If there found any problem with the Chipcell Carbon, please replace it.

13) Use of Functional Coating Chemicals

Some solvents of functional coating chemicals which applied on the same PCB with the Chipcell Carbon may cause undesired effects on the Chipcell Carbon such as surface oxidation or electrolyte leakage. When apply those chemicals, be careful of not coating the Chipcell Carbon's surface.

13. Leakage Level Criteria

Level	Appearance of Leakage	Definition
Level 1		Leakage can not be recognizable with naked eyes, it can be recognizable only by microscope (magnification of 10 or more)
Level 2		Leakage can be recognizable by naked eyes. But there is no bridge between cap(-) and case(+).
Level 3		Leakage reaches the flat line of cap(-) or flow down to side of case(+). Leaked bridge between cap(-) and case(+) is observed.

14. Environmental Management

All Chipcell Carbon products are RoHS 1, 2 and 3 compliant, Halogen Free and environment friendly.

Series	RoHS 1,2 directive (Pb, Cr+6, Hg, Cd, PBB, PBDE)	ELV directive (Pb, Cr+6, Hg, Cd)	PVC	Halogen Flame Retardant Free (Cl, Br)	RoHS 3 directive (DEHP, BBP, DBP, DIBP)	etc.
DMS	N.D.	N.D.	N.D.	N.D.	N.D.	

* N.D. : Not Detected or Within Permitted Range